## Amendments to the Specification:

Please replace paragraph [02] with the following amended paragraph:

[2] This application is a continuation of U.S. Utility Patent Application No. 09/493,496, filed January 28, 2000, now US Patent No. 6,790,377, which is a divisional of U.S. Patent Application No. 09/055,183, filed April 3, 1998, now U.S. Patent No. 6,027,630; which in turn claims ~~priority~~ benefit to U.S. Provisional Patent Application No. 60/043,742, filed on April 4, 1997. Each of these prior applications is incorporated herein by reference as if set forth in full.

Please replace paragraph [138] with the following amended paragraph:

[138] For elements (e.g., devices) that require dozens or hundreds of deposited layers, the electroplating system can be arranged in an annular design in which the electroplating articles are arranged in rings and in which the individual electroplating articles are replaced after having contacted each of the substrates to be plated. One example of an apparatus for mass-producing electroplated structures is shown in Fig. 20. Apparatus 78 is designed to process 24 eight-inch diameter substrates 2. Apparatus 78 is concentric in design and includes an outer ring 80, and a middle ring 82 and a central disk 85. Outer ring 80 includes electrolyte bath 84 and electroplating articles (not shown) for selectively plating a first metal. Middle ring 82 includes an electrolyte bath 86 for blanket-plating a second metal. As opposed to blanket plating, middle ring 82 can include electroplating articles for selectively plating the second metal. A rotating ~~Rotating~~ lapping plate ~~85~~ (if required), for planarizing the plated metal layers, is located at the center of apparatus 78. All processes (first metal selective plating, second metal blanket or selective plating and, optionally, planarization) occur during a single cycle, but on different substrates 2. At the end of the cycle, the substrates undergoing plating move in the pattern shown, in part, by arrows. Eight layers have been deposited after having completed all of the cycles in the system and arriving back at the starting point. Prior to the first substrate arriving back at the first plating article, the first plating article can be replaced by a new plating article. Likewise after the other plating articles have contacted each of the substrates they can be replaced, and substrates 2 can continue around apparatus 78, receiving as many layers as are required for the device being made. Rinsing stations are not shown but can be located in the spaces between the plating articles. It is anticipated that such an apparatus would permit

the simultaneous manufacture of about 2.5 million devices, each 500 microns square by 200 microns tall, in an 8-hour period.